

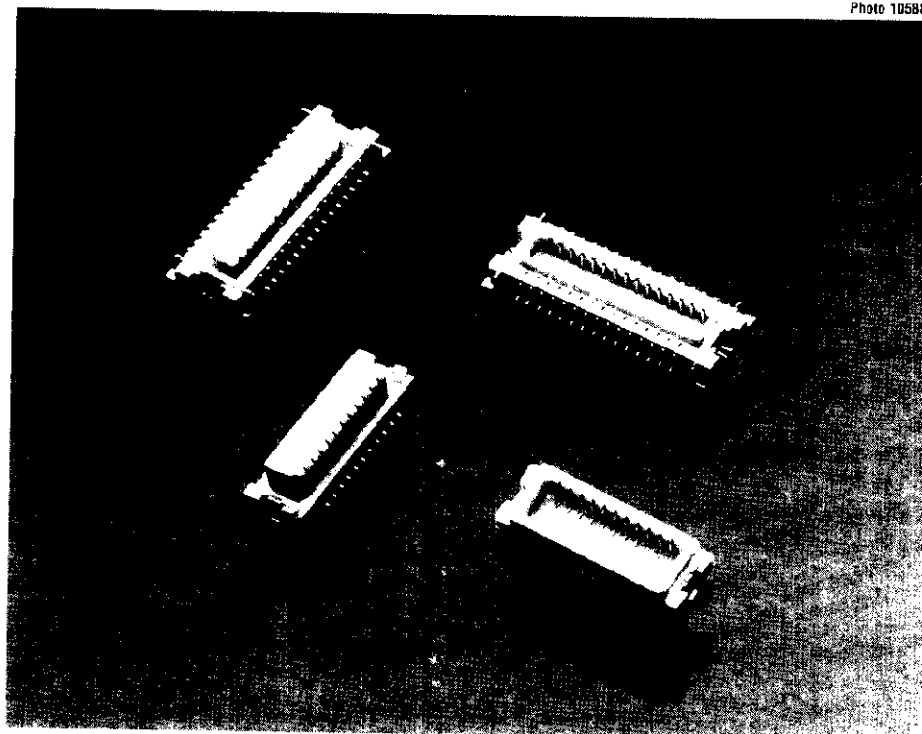


0.8mm Fine Stack and Fine Mate Connectors

Photo 105880

Product Facts

- 0.8 [.031] fine pitch SMT connectors for board-to-board interconnections
- Low profile parallel board stacking heights as low as 3.0 [.118]
- Available packaged in tape and reel for automatic placement per EIAJ standards
- Offered with tin or gold plating on mating surfaces
- Solder pegs included for anti-peeling
- Surface areas provided to accommodate vacuum nozzles



Note: Fine Stack connectors are shown on top; Fine Mate connectors are shown at the bottom.

The AMP 0.8mm Fine Stack and Fine Mate product lines are economical, surface-mount, fine pitch board-to-board connectors. Both product lines have been developed to meet the latest needs of the electronic industry for high density packaging.

These connectors offer a 0.8 [.031] contact pitch and parallel board stacking heights ranging from 3.0 [.118] to 4.5 [.177]. They are ideally suited for applications requiring miniaturization, such as cellular phones, pagers, notebook computers, camcorders and other consumer electronics.

Both Fine Stack and Fine Mate connectors were designed for economical, automatic placement onto SMT printed circuit boards. The plug and cap designs include surface areas to accommodate "pick and place" vacuum nozzles without secondary covers. All products are "tape and reel" packaged, conforming to EIAJ standards.

0.8mm Fine Stack/Fine Mate
Connectors